CORNEY)

DECLAP N FOR PATENT APPLICATION (WITH POWER OF

As an inventor named below or on any attack of continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled TECHNIQUE FOR ELIMINATION OF PITTING ON SILICON SUBSTRATE DURING GATE STACK ETCH, the specification of which (check one):

I is attached hereto.	tes application serial no. 08/682,935 and was	amended on .		
was filed on as PCT in	ternational application no and wa	s amended under PCT Article I9 on	·	
I hereby state that I have reviewed and	understand the contents of the above-identified	specification, including the claims, as amend	led by any am	endment
referred to above.				
I acknowledge the duty to disclose to the	e U.S. Patent and Trademark Office all informeriality" is defined in Title 37, Code of Federa	nation known to me to be material to the pate	ntability of the	e subject
certificate or § 365(a) of any PCT internat	under Title 35, United States Code, § 119 (a)- ional application(s) designating at least one co- lentified below and on any attached continuation nating at least one country other than the Unite	untry other than the United States of America on page any foreign application for patent or i	listed below a inventor's cert	and on any
Prior foreign/PCT application(s):			Priority Claimed	
(number)	(country)	(day/month/year filed)	Yes	No
(number)	(country)	(day/month/year filed)	Yes	No
the duty to disclose to the U.S. Patent and Regulations § 1.56 which became available (application serial no.)	Trademark Office all information known to me between the filing date of such prior applicat (filing date)	ion and the national or PCT international filin	ng date of this	application
(application serial no.)	(filing date)	(status - pending, patented or	abandoned)	
· • •	5, United States Code, § 119(e) of any United	States provisional application(s) listed below:		
(provisional application no.)	(filing date)	-		
(provisional application no.)	(filing date)	-		
(provisional application no.)	(filing date)	-		
I hereby appoint the following Register connected therewith:	ed Practitioners to prosecute this application a	nd to transact all business in the Patent and T	rademark Offi	ice
David V. Trask, Reg. No. 22,012 Laurence B. Bond, Reg. No. 30,549 Allen C. Turner, Reg. No. 33,041 Robert G. Winkle, Reg. No. 37,474 W. Bryan Farney, Reg. No. 32,651	William S. Britt, Reg. No. 20,969 Joseph A. Walkowski, Reg. No. 28,765 Alan K. Aldous, Reg. No. 31,905 Patrick McBride, Reg. No. 39,295 Michael L. Lynch, Reg. No. 30,871	Thomaa J. Rossa, Reg. No. 26,799 James R. Duzan, Reg. No. 28,393 Julie K. Morrisa, Reg. No. 33,263 Edgar R. Cataxinos, Reg. No. 39,931 Lia M. Pappaa, Reg. No. 34,095	l	
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		has all assessment and an information and be	aliaf ara halias	ued to be

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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Invention title: TECHNIQUE FOR ELIMINATION OF PITTING ON SILICON SUBSTRATE DURING GATE STACK ETCH

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